AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (canceled).

2. (currently amended): A compression bonding method comprising:

disposing a first plurality of metal bonding film shapes in a pattern on a substrate and disposing a second plurality of metal bonding film shapes in a pattern on a bonded element; and

disposing the bonded element above the first plurality of metal bonding film shapes and applying heat to the substrate and pressure to the bonded element, thereby bonding the bonded element having the second plurality of metal bonding film shapes to the substrate having the first plurality of metal bonding film shapes,

wherein the first plurality of metal bonding film shapes are spaced apart from each other; and

wherein the first plurality of metal bonding film shapes and the second plurality of metal bonding film shapes are each disposed in patterns on the substrate and bonded element, respectively, prior to the application of heat to the substrate and pressure to the bonded element.

3-8. (canceled).

9. (previously presented): The compression bonding method of claim 2, wherein the substrate is made of a material selected from the group consisting of silicon, metal, and ceramic.

10. (previously presented): The compression bonding method of claim 2, wherein the first and second plurality of metal bonding film shapes are made of a material selected from the group consisting of aluminum, magnesium, zinc, and titanium.

11. (previously presented): The compression bonding method of claim 2, wherein the first and second plurality of metal bonding film shapes are stripes or dots.

12. (previously presented): The compression bonding method of claim 2, wherein the bonded element is glass or metal.

13. (previously presented): The compression bonding method of claim 2, wherein the heat is lower than 350°C.

14. (previously presented): The compression bonding method claim 2, wherein the bonded element contacts more than one of the first and second plurality of metal bonding film shapes.